

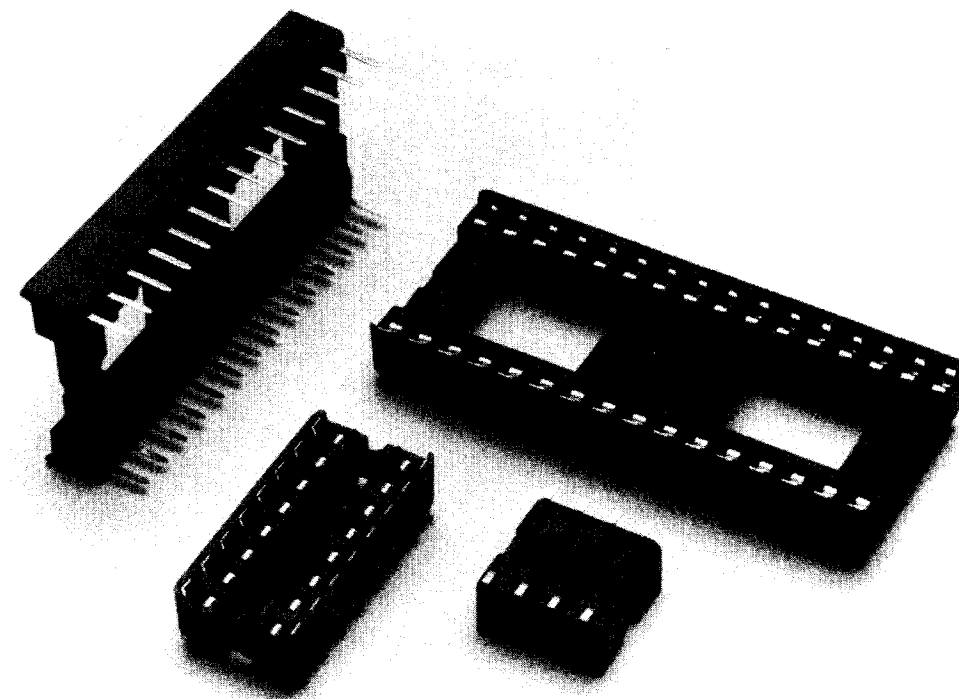


DIP Sockets (Continued)

Dual Leaf (DL), Surface Mount and Surface Mount Compatible

Product Facts

- Dual wiping, dual leaf contact design for high reliability and constant low resistance
- Anti-overstress prevents contact damage
- Sealed "true closed bottom" inhibits solder wicking and flux contamination
- Robotic compatibility facilitates automatic assembly-vacuum pick-up
- Choice of tin- or gold-plated contacts for wider versatility
- Stable and co-planer soldertails yield reliable surface mounting to pc board
- High temperature plastic and contact material are compatible with VPR and IR soldering
- Recognized under the Component Program of Underwriters Laboratories Inc., File E28476
- Certified by Canadian Standards Association File No. LR 7189



The AMP DIPLOMATE family of DIP sockets has recently been expanded to include products designed for surface mounting.

Available in dual leaf (DL) versions, these surface mount sockets combine the proven features of AMP's standard DIPLOMATE products with those specifically designed for vapor phase reflow (VPR) and infrared (IR) soldering, such as gull wing solder tails and high temperature housing and contact materials. All AMP surface mount DIPLOMATE sockets are co-planer for reliable mounting and feature an anti-overstress contact design to prevent contact damage.

DL sockets feature reliable dual face wiping contacts with tin or gold plating over economical phosphor bronze base material. Housings are compatible with

commercially available automatic insertion equipment and feature a "true closed bottom" design which prevents solder and flux wicking.

Also available are through-hole DL sockets that are solder process compatible with existing surface mount components.

Performance Characteristics

- Rating** — Signal application only
- Contact Resistance** — 20 milliohms max. (initial)
30 milliohms max. (after test)
- Dielectric Withstanding Voltage** — 1000 VRMS min.
- Insulation Resistance** — 10,000 megohms min. initial
- Operating Temperature** — -25°C to +105°C (Tin)
-55°C to +125°C (Gold)
- Vibration** — 15 Gs, 10-2000-10 Hz
- Physical Shock** — 100 Gs
- Mating Force** — 340 grams per contact
- Contact Retention** — 340 grams per contact
- Contact Separating Force** — 25 grams min.
- Durability** — 25 cycles

Technical Documents

Product Specifications — 108-1066

Application Specifications — 114-1044
114-1052



DIP Sockets (Continued)

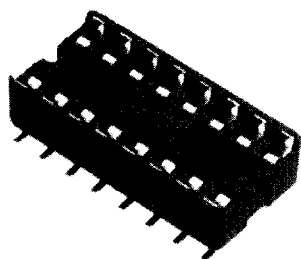
Dual Leaf (DL), Surface Mount and Surface Mount Compatible (Continued)

Sockets accept 0.2—0.36
[.008—.014] thick IC leads

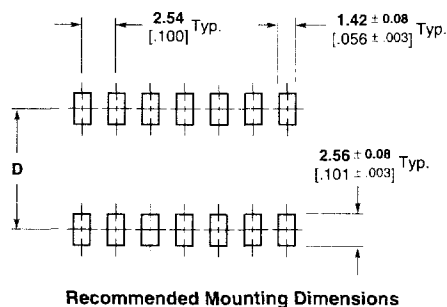
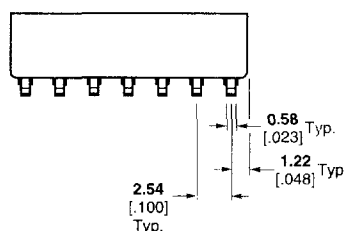
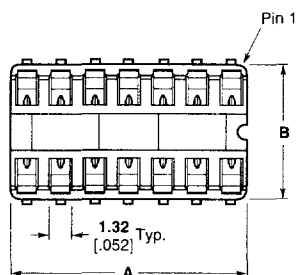
Material and Finish

Housing — PCT Glass reinforced,
94V-0 rated, brown*

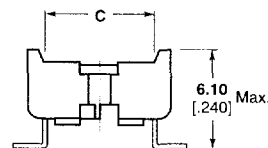
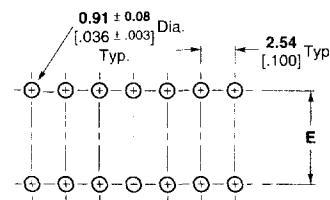
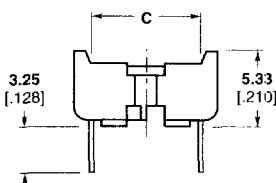
Contacts — Phosphor bronze or
beryllium copper with tin or gold plating
(see table)



*14-position part numbers (X-382463-X)
are glass filled polyester, 94V-0 rated,
black



Recommended Mounting Dimensions

Optional Surface Mount Compatible Through-Hole Sockets²

Recommended Mounting Dimensions

No. of Pos.	Dimensions					Phosphor Bronze				Beryllium Copper	
	A	B	C	D	E	Surface Mount ¹		Through-Hole ^{1,2}		Surface Mount ¹	Through-Hole ^{1,2}
						Tinned	Gold Plate ³	Tinned	Gold Plate ³		
8	10.03 .395	10.01 .394	8.15 .321	8.89 .350	7.62 .300	2-382401-3	2-382401-4	2-382462-3	2-382462-4	2-382401-1	2-382462-1
14	17.65 .695	10.01 .394	8.15 .321	8.89 .350	7.62 .300	2-382402-3	2-382402-4	2-382463-3 ⁴	2-382463-4 ⁴	2-382402-1	2-382463-1 ⁴
16	20.19 .795	10.01 .394	8.15 .321	8.89 .350	7.62 .300	2-382403-3	2-382403-4	2-382464-3	2-382464-4	2-382403-1	2-382464-1
18	22.73 .895	10.01 .394	8.15 .321	8.89 .350	7.62 .300	2-382404-3	—	2-382557-3	—	2-382404-1	2-382557-1
20	25.27 .995	10.01 .393	8.15 .321	8.89 .350	7.62 .300	2-382405-3	2-382405-4	2-382465-3	2-382465-4	2-382405-1	2-382465-1
24	30.35 1.195	17.63 .694	15.77 .621	16.51 .650	15.24 .600	2-382408-3	2-382408-4	2-382466-3	2-382466-4	2-382408-1	2-382466-1
28	35.43 1.395	10.01 .394	15.77 .621	8.89 .350	7.62 .300	—	—	—	—	2-382636-1	—
28	35.43 1.395	17.63 .694	15.77 .621	16.51 .650	15.24 .600	2-382409-3	2-382409-4	2-382467-3	2-382467-4	2-382409-1	2-382467-1
32	40.51 1.595	17.63 .694	15.77 .621	16.51 .650	—	2-382424-3	2-382424-4	2-382470-3	2-382470-4	2-382424-1	2-382470-1
40	50.67 1.995	17.63 .694	15.77 .621	16.51 .650	15.24 .600	2-382411-3	2-382411-4	2-382468-3	2-382468-4	2-382411-1	2-382468-1

¹ All parts packaged in plastic tubes. See page 76 for quantities.

² Through-hole sockets are compatible with surface mount soldering practices except where noted.

³ Two 0.00038 [.000015] min. thick gold stripes in contact area with tin-lead (93/7) on solder tails and nickel on balance of contact.

⁴ Not compatible with surface mount soldering practices.



DIP Sockets (Continued)

Package Quantities

No. of Socket Pos.	Contact Spacing	Quantity Per Tube	Tubes Per Box	Total Quantity Per Box
6	7.62 .300	70	100	7000
8	7.62 .300	52	100	5200
14	7.62 .300	30	100	3000
16	7.62 .300	26	100	2600
18	7.62 .300	23	100	2300
20	7.62 .300	21	100	2100
22	7.62 .300	19	100	1900
22	10.16 .400	19	80	1520
24	7.62 .300	17	100	1700
24	10.16 .400	17	80	1360
24	15.24 .600	17	100	1700
28	7.62 .300	15	100	1500
28	15.24 .600	15	100	1500
32	15.24 .600	13	100	1300
40	15.24 .600	10	100	1000
42	15.24 .600	10	100	1000
48	15.24 .600	8	100	800
64	22.86 .900	18 ¹	20	360

¹ Tray packaged.